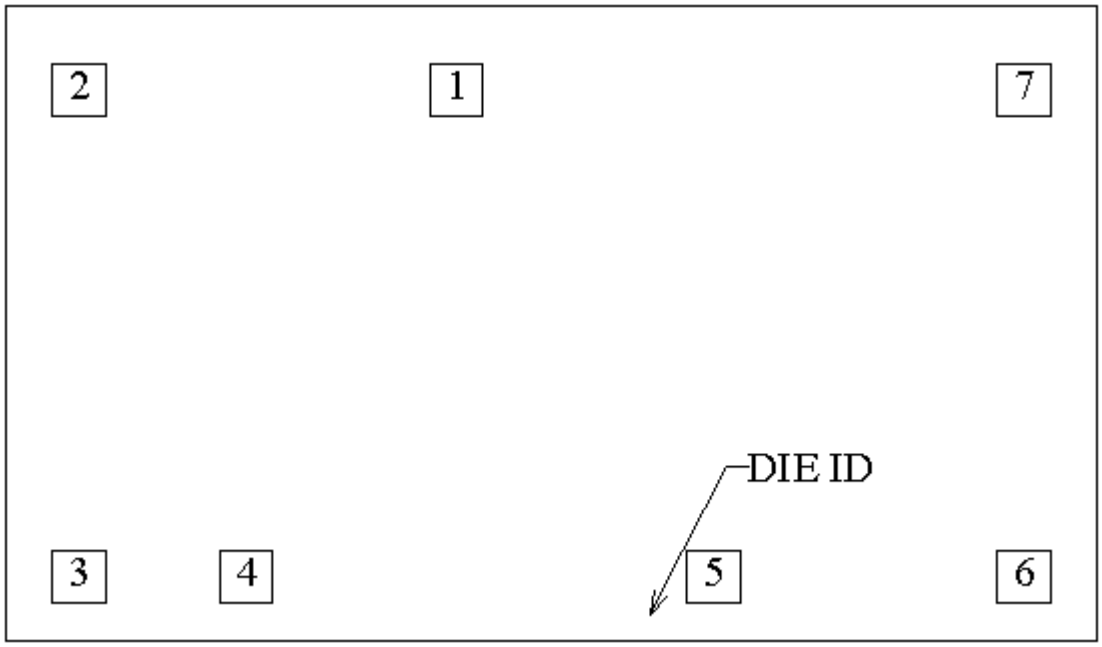
LF156 MW8 MCD2500A
JFET INPUT OPERATIONAL AMPLIFIERS

March 06,2007

DIE LAYOUT (C -STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	156C	Bond Pad Opening Size (min)	91µm x 91µm
Die Step	C	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1880µm x 1092µm 74.0mils x 43.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	287µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
Balance	1	-163	402	91	x	91
IN-	2	-813	402	91	x	91
IN+	3	-813	-436	91	x	91
V-	4	-526	-436	91	x	91
Balance	5	279	-436	91	x	91
Output	6	813	-436	91	x	91
V+	7	813	402	91	x	91

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